Yuyang Wang

APPOINTMENTS

Columbia University in the City of New York

Postdoctoral Research Scientist, Columbia Nano Initiative

New York, New York, USA 2021-Present

EDUCATION

University of California, Santa Barbara

Ph.D. in Electrical and Computer Engineering

Santa Barbara, California, USA 2018-2021

University of California, Santa Barbara

M.S. in Electrical and Computer Engineering

Santa Barbara, California, USA 2015-2018

Tsinghua University

B.Eng. in Electronic Engineering

Beijing, China 2011-2015

PUBLICATIONS

Refereed Journal Papers

- J1 A. James, A. Rizzo, Y. Wang, A. Novick, S. Wang, R. Parsons, K. Jang, M. Hattink, and K. Bergman, "Process Variation-Aware Compact Model of Strip Waveguides for Photonic Circuit Simulation," Journal of Lightwave Technology, vol. Early Access, pp. 1–14, 2023. **ᡂ** 10.1109/JLT.2023.3238847.
- J2 Y. Wang, P. Sun, J. Hulme, M. A. Seyedi, M. Fiorentino, R. G. Beausoleil, and K.-T. Cheng, "Energy Efficiency and Yield Optimization for Optical Interconnects via Transceiver Grouping," Journal of Lightwave Technology, vol. 39, no. 6, pp. 1567–1578, Mar. 2021. 10.1109/JLT.2020.3039489.
- Z. Zhang, R. Wu, Y. Wang, C. Zhang, E. J. Stanton, C. L. Schow, K.-T. Cheng, and J. E. Bowers, "Compact Modeling for Silicon Photonic Heterogeneously Integrated Circuits," Journal of Lightwave Technology, vol. 35, no. 14, pp. 2973–2980, Jul. 2017. 6 10.1109/JLT.2017.2706721.

Refereed Conference Papers

- C1 A. James, Y. Wang, A. Rizzo, and K. Bergman, "Flexible, Process-Aware Compact Model of Effective Index in Silicon Waveguides for Commercial Foundries," in 2022 International Conference on Numerical Simulation of Optoelectronic Devices (NUSOD), Turin, Italy: IEEE, Sep. 2022, pp. 173–174. 10.1109/NUSOD54938.2022.9894784.
- C2 Y. Wang and K.-T. Cheng, "Traffic-Adaptive Power Reconfiguration for Energy-Efficient and Energy-Proportional Optical Interconnects," in 2021 IEEE/ACM International Conference On Computer Aided Design (ICCAD), Munich, Germany: IEEE, Nov. 2021, pp. 1-9. 6 10.1109/ICCAD51958.2021.9643475.
- Y. Wang, J. Hulme, P. Sun, M. Jain, M. A. Seyedi, M. Fiorentino, R. G. Beausoleil, and K.-T. Cheng, "Characterization and Applications of Spatial Variation Models for Silicon Microring-Based Optical Transceivers," in 2020 57th ACM/IEEE Design Automation Conference (DAC), San Francisco, CA, USA: IEEE, Jul. 2020, pp. 1–6. (2010) 10.1109/DAC18072.2020.9218608.
- C4 Y. Wang and K.-T. Cheng, "Task Mapping-Assisted Laser Power Scaling for Optical Network-on-Chips," in 2019 IEEE/ACM International Conference on Computer-Aided Design (ICCAD), Westminster, CO, USA: IEEE, Nov. 2019, pp. 1-6. 6 10.1109/ICCAD45719.2019.8942146.
- C5 Y. Wang, M. A. Seyedi, J. Hulme, M. Fiorentino, R. G. Beausoleil, and K.-T. Cheng, "Bidirectional tuning of microring-based silicon photonic transceivers for optimal energy efficiency," in Proceedings of the 24th Asia and South Pacific Design Automation Conference, Tokyo Japan: ACM, Jan. 2019, pp. 370–375. 4 10.1145/3287624.3287649.
- Y. Wang, M. A. Seyedi, R. Wu, J. Hulme, M. Fiorentino, R. G. Beausoleil, and K.-T. Cheng, "Energy-efficient channel alignment of DWDM silicon photonic transceivers," in 2018 Design, Automation & Test in Europe Conference & Exhibition (DATE), Dresden, Germany: IEEE, Mar. 2018, pp. 601–604. @ 10.23919/DATE.2018.8342079.
- R. Wu, M. A. Seyedi, Y. Wang, J. Hulme, M. Fiorentino, R. G. Beausoleil, and K.-T. Cheng, "Pairing of microring-based silicon photonic transceivers for tuning power optimization," in 2018 23rd Asia and South Pacific Design Automation Conference (ASP-DAC), Jeju: IEEE, Jan. 2018, pp. 135–140. 10.1109/ASPDAC.2018.8297295.

Last updated: February 16, 2023

- C8 R. Wu, **Y. Wang**, Z. Zhang, C. Zhang, C. L. Schow, J. E. Bowers, and K.-T. Cheng, "Compact modeling and circuit-level simulation of silicon nanophotonic interconnects," in *Design, Automation & Test in Europe Conference & Exhibition (DATE)*, 2017, Lausanne, Switzerland: IEEE, Mar. 2017, pp. 602–605. 10.23919/DATE.2017.7927057.
- C9 A. Ghofrani, M. A. Lastras-Montaño, **Y. Wang**, and K.-T. Cheng, "In-place Repair for Resistive Memories Utilizing Complementary Resistive Switches," in *Proceedings of the 2016 International Symposium on Low Power Electronics and Design*, San Francisco Airport CA USA: ACM, Aug. 2016, pp. 350–355. 10.1145/2934583.2934590.
- C10 C. Xu, F. X. Lin, **Y. Wang**, and L. Zhong, "Automated OS-level Device Runtime Power Management," in *Proceedings of the Twentieth International Conference on Architectural Support for Programming Languages and Operating Systems*, Istanbul Turkey: ACM, Mar. 2015, pp. 239–252. 10.1145/2694344.2694360.

Invited Conference Papers

Y. Wang, L. Shao, M. A. Lastras-Montano, and K.-T. Cheng, "Taming Emerging Devices' Variation and Reliability Challenges with Architectural and System Solutions [Invited]," in 2019 IEEE 32nd International Conference on Microelectronic Test Structures (ICMTS), Kita-Kyushu City, Fukuoka, Japan: IEEE, Mar. 2019, pp. 90–95. 10.1109/ICMTS.2019.8730924.

TALKS AND PRESENTATIONS

 Ph.D. Forum at the 57th ACM/IEEE Design Automation Conference (DAC), online virtual event Design and Optimization of Variation-Aware Runtime-Reconfigurable Optical Interconnects Jun. 2020

- Invited talk at the 4th **Optical/Photonic Interconnects for Computing Systems (OPTICS) workshop**, Dresden, Germany Mar. 2018 Optimal Pairing and Non-Uniform Channel Alignment of Microring-based Transceivers for Comb Laser-Driven DWDM Silicon Photonics
- Invited talk at the ECE Departmental Seminar, Hong Kong University of Science and Technology Variation-Aware Modeling and Design of Silicon Photonic Systems

Jan. 2018

ACTIVITIES

• Teaching Assistant at the University of California, Santa Barbara

ECE 153B: Sensor & Peripheral Interface Design

Winter 2019

· Reviewer of refereed journals

2018–Present

- IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, IEEE Transactions on Very Large Scale Integration (VLSI) Systems, IEEE Access.
- Textbook Translation
 - T1 C. Hawkins, J. Segura, and P. Zarkesh-Ha, *CMOS Digital Integrated Circuits: A First Course (Chinese Edition)*, trans. by **Y. Wang** and Y. Yin. China Machine Press, 2016, original work published by the Institution of Engineering and Technology (IET) in 2013.
 - T2 S. Kundu and A. Sreedhar, *Nanoscale CMOS VLSI Circuits: Design for Manufacturability (Chinese Edition)*, trans. by **Y. Wang** and W. Xie. China Science Publishing, 2014, original work published by McGraw-Hill Education in 2010.

REFERENCES

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Kwang-Ting Cheng

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